



US009250273B2

(12) **United States Patent**
Nagao

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(45) **Date of Patent:** **Feb. 2, 2016**

(54) **CURRENT SENSOR**

USPC 324/117 H, 117 R, 126, 127, 156, 157,
324/227, 228, 236, 244, 253
See application file for complete search history.

(71) Applicant: **FUJITSU COMPONENT LIMITED**,
Tokyo (JP)

(56) **References Cited**

(72) Inventor: **Naoyuki Nagao**, Tokyo (JP)

U.S. PATENT DOCUMENTS

(73) Assignee: **FUJITSU COMPONENT LIMITED**,
Tokyo (JP)

5,391,986 A * 2/1995 Sauerbaum G01N 27/74
324/204
7,316,576 B2 * 1/2008 Saito et al. 439/76.2

(*) Notice: Subject to any disclaimer, the term of this
patent is extended or adjusted under 35
U.S.C. 154(b) by 244 days.

(Continued)

FOREIGN PATENT DOCUMENTS

(21) Appl. No.: **13/933,796**

JP	6-16879	3/1994
JP	2002-243768	8/2002
JP	2011-17618	1/2011
JP	2011-159464	8/2011
JP	2012-122793	6/2012

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(65) **Prior Publication Data**

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OTHER PUBLICATIONS

(30) **Foreign Application Priority Data**

Patent Abstracts of Japan, Publication No. 2002-243768, Published
Aug. 28, 2002.

Sep. 20, 2012 (JP) 2012-206661

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(51) **Int. Cl.**

G01R 33/04	(2006.01)
G01R 15/20	(2006.01)
G01R 19/15	(2006.01)
G01R 19/00	(2006.01)
G01R 1/20	(2006.01)
G01R 33/07	(2006.01)

Primary Examiner — Jay Patidar

Assistant Examiner — Raul Rios Russon

(74) *Attorney, Agent, or Firm* — Staas & Halsey LLP

(52) **U.S. Cl.**

CPC **G01R 19/15** (2013.01); **G01R 1/203**
(2013.01); **G01R 15/202** (2013.01); **G01R**
15/207 (2013.01); **G01R 19/0092** (2013.01);
G01R 19/00 (2013.01)

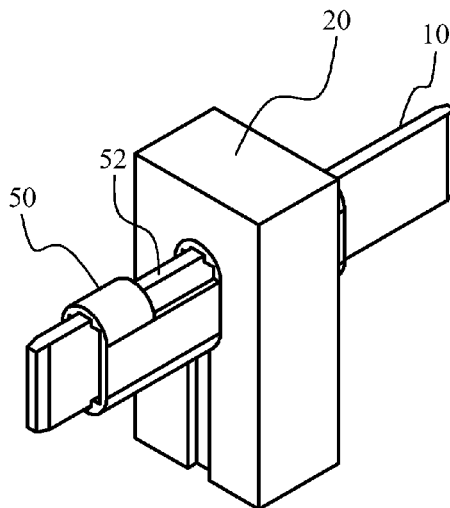
(57) **ABSTRACT**

A current sensor includes: a current bar through which a
current flows; a first cover that covers the current bar and
includes a cutout portion formed in at least a part thereof; a
magnetic substance core that covers at least parts of the cur-
rent bar and the first cover and includes a gap; a magnetic field
measuring element located in the gap; and a second cover that
covers the magnetic substance core and the magnetic field
measuring element and at least parts of the current bar and the
first cover, and is located so that a side surface thereof engages
with the cutout portion of the first cover.

(58) **Field of Classification Search**

CPC G01R 33/02; G01R 15/202; G01R 33/07;
G01R 33/18; G01R 19/0092; G01R 1/203;
G01R 15/207; G01R 19/00

13 Claims, 25 Drawing Sheets



(56)

References Cited

2013/0187633 A1* 7/2013 Yasui G01R 15/207
324/117 R

U.S. PATENT DOCUMENTS

7,615,986 B2* 11/2009 Nomoto et al. 324/117 H
8,237,435 B2* 8/2012 Hashio et al. 324/244
2004/0080308 A1* 4/2004 Goto 324/117 H
2011/0006753 A1 1/2011 Yu et al.
2011/0068771 A1* 3/2011 Ueno G01R 15/202
324/117 R
2011/0187348 A1 8/2011 Soneda et al.
2012/0217964 A1* 8/2012 Iizuka G01R 33/0029
324/253

OTHER PUBLICATIONS

Patent Abstracts of Japan, Publication No. 2011-017618, Published
Jan. 27, 2011.
Patent Abstracts of Japan, Publication No. 2011-159464, Published
Aug. 18, 2011.
Patent Abstracts of Japan, Publication No. 2012-122793, Published
Jun. 28, 2012.

* cited by examiner

FIG. 1A

100

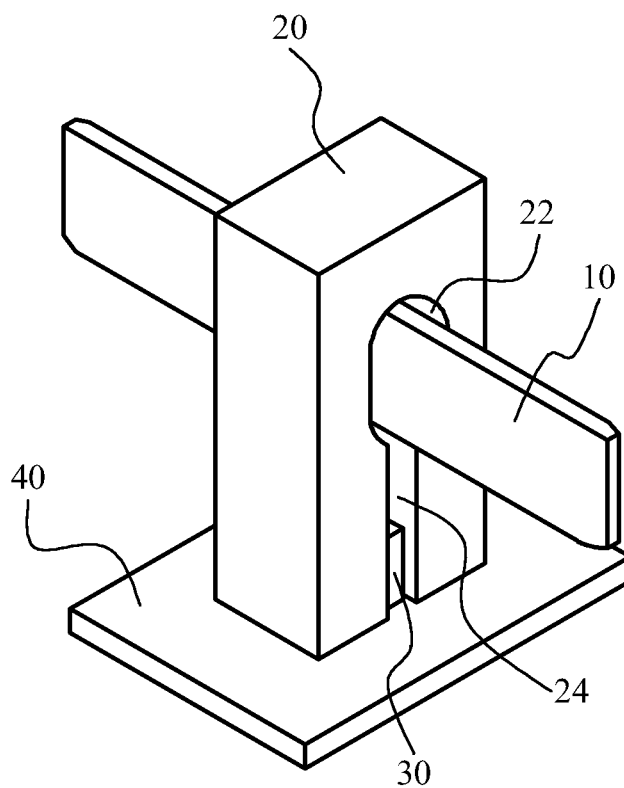


FIG. 1B

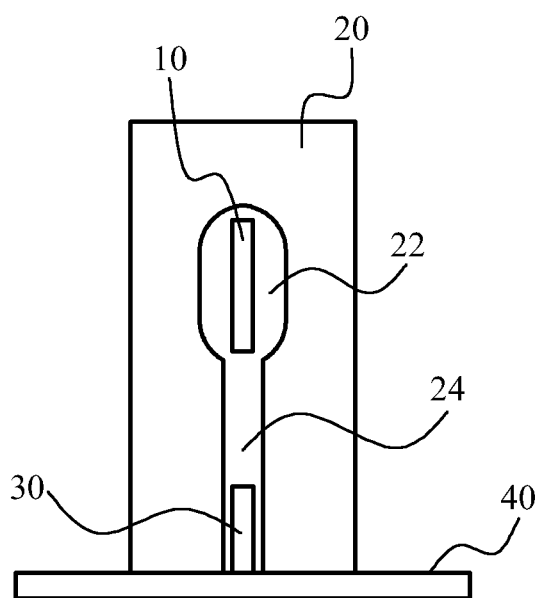


FIG. 2A

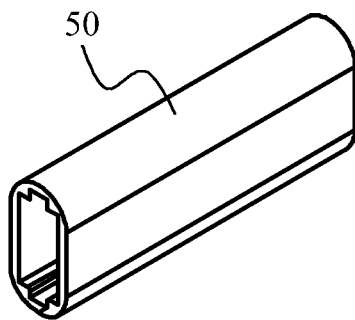


FIG. 2B

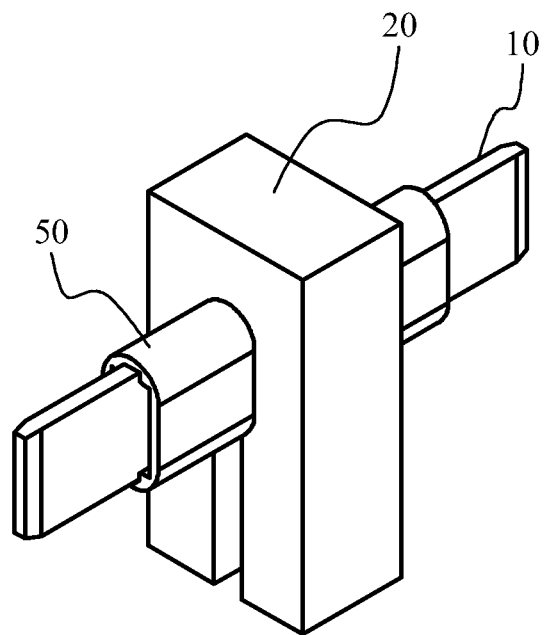


FIG. 3A

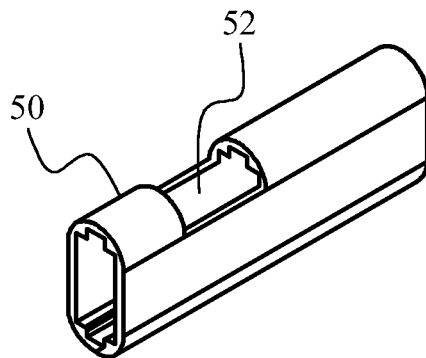


FIG. 3B

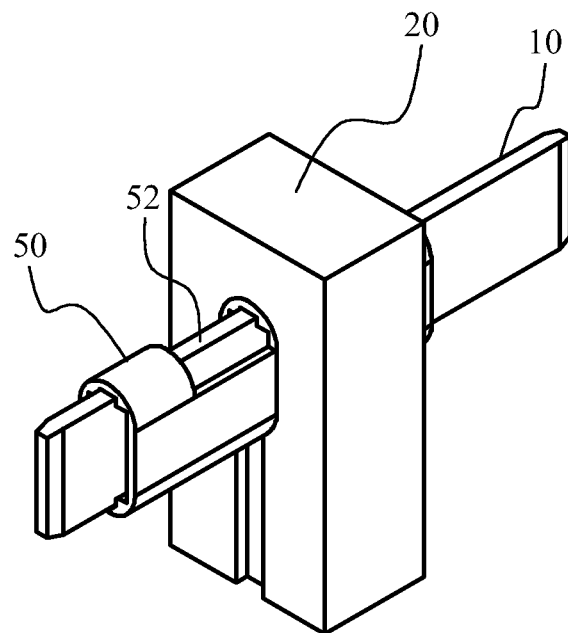


FIG. 4A

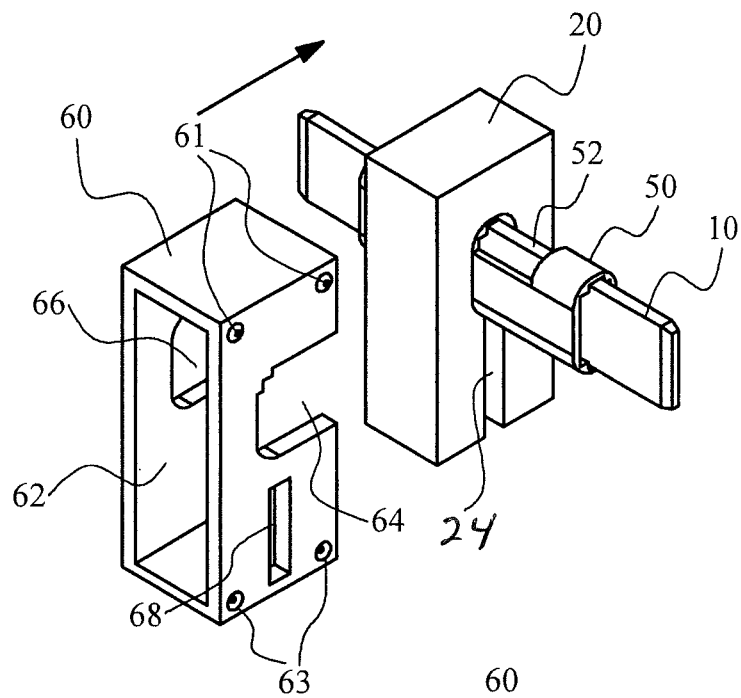


FIG. 4B

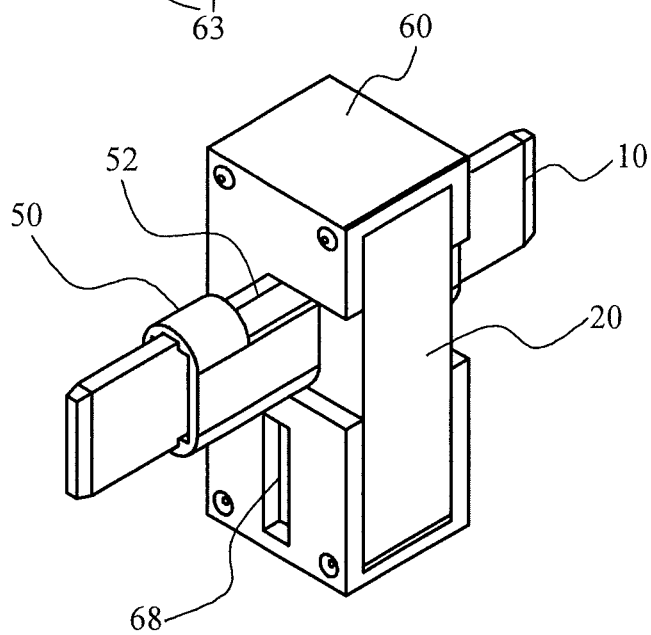


FIG. 5A

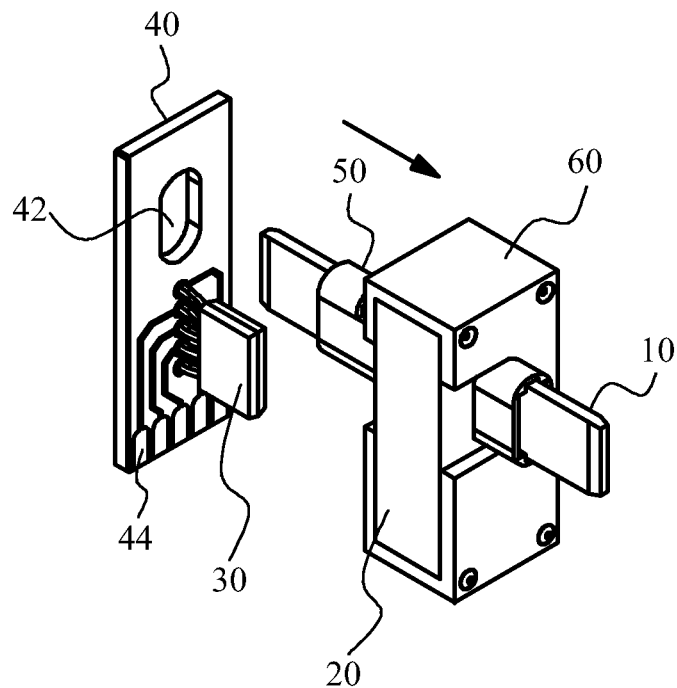


FIG. 5B

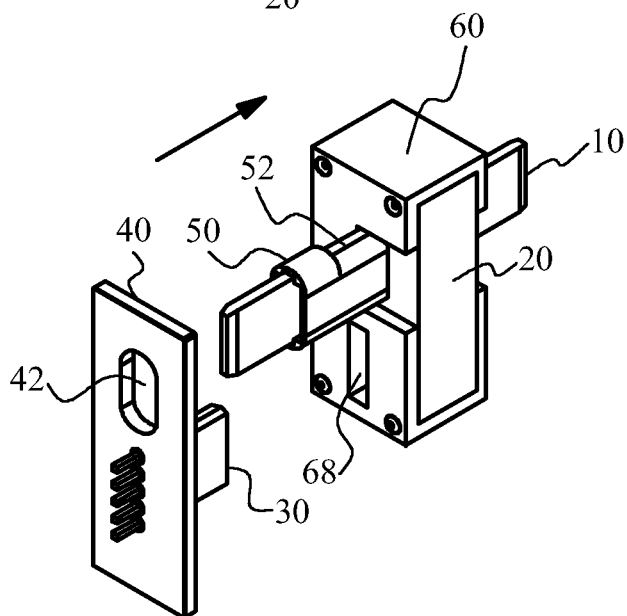


FIG. 6A

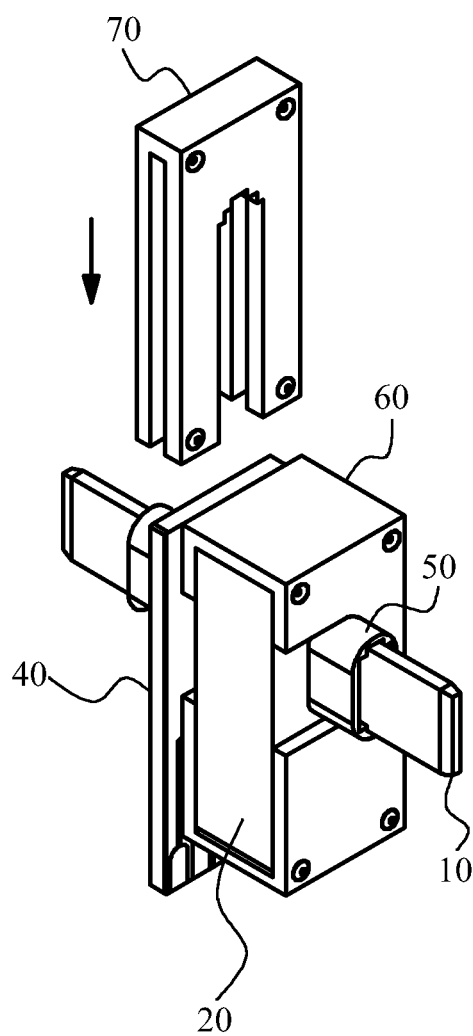


FIG. 6B

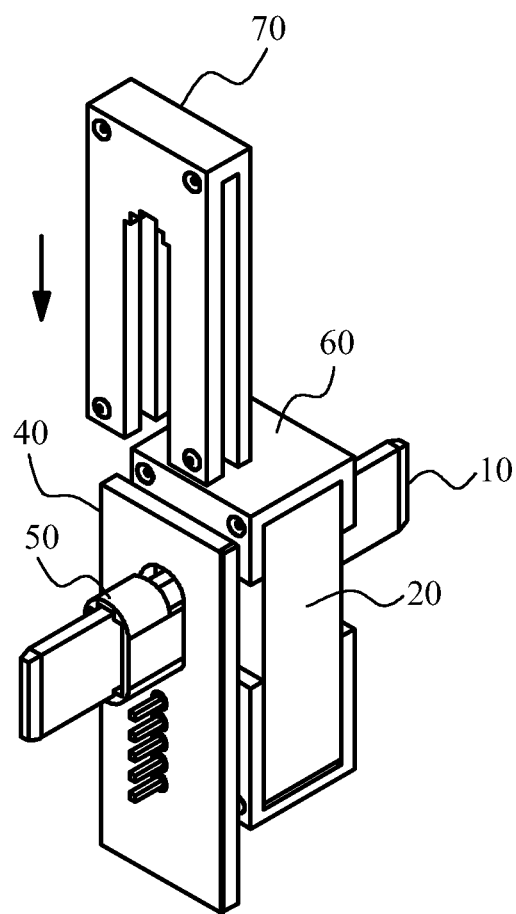


FIG. 7A

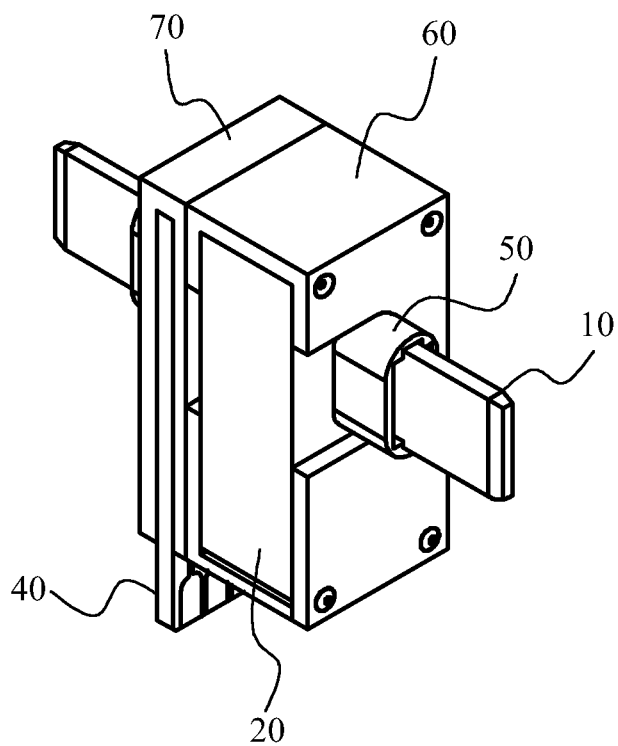


FIG. 7B

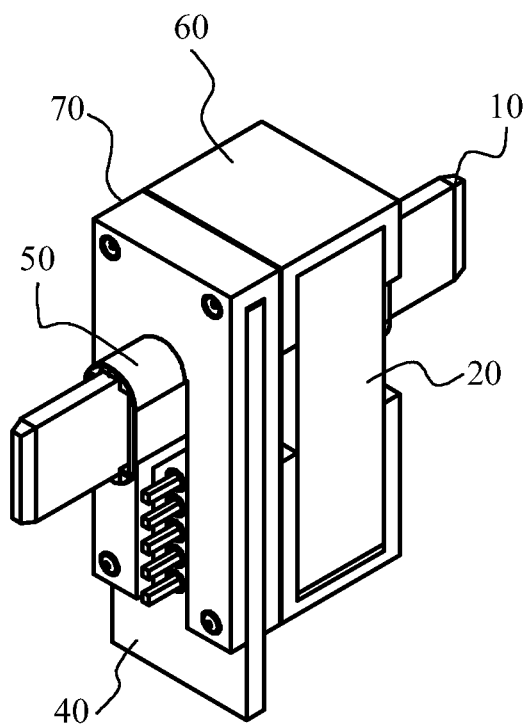


FIG. 8A

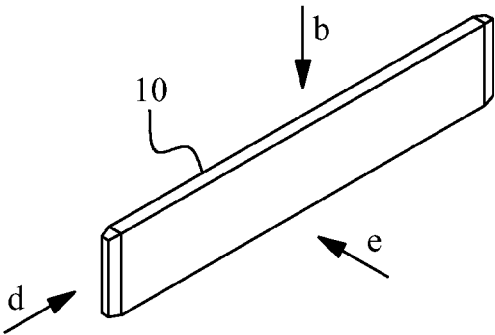


FIG. 8B



FIG. 8C



FIG. 8D

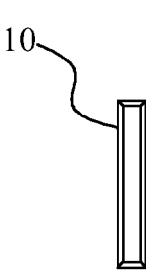


FIG. 9A

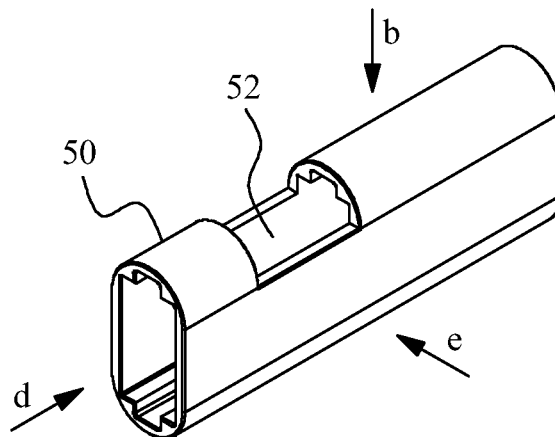


FIG. 9B

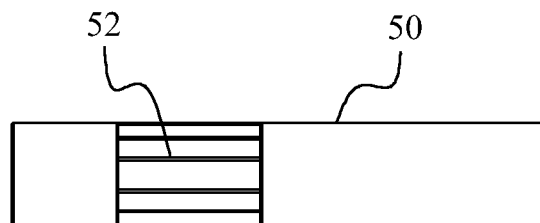


FIG. 9C

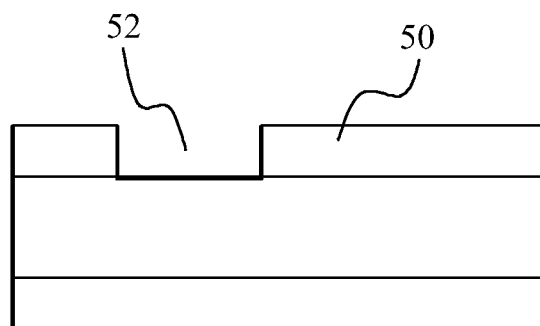


FIG. 9D

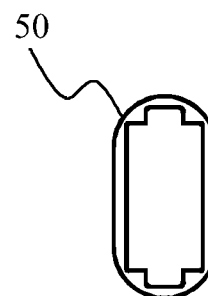


FIG. 10A

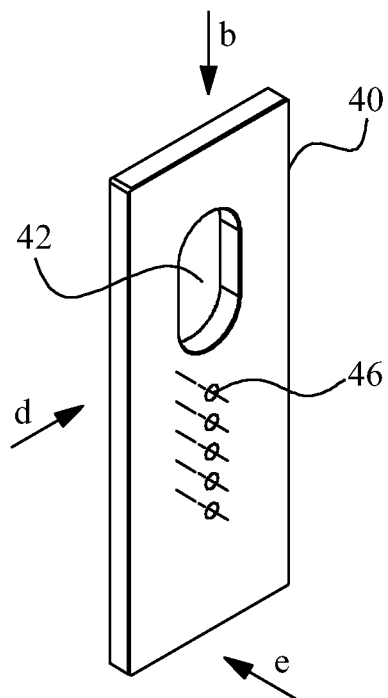


FIG. 10B

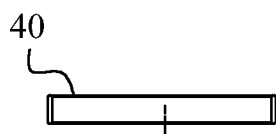


FIG. 10C

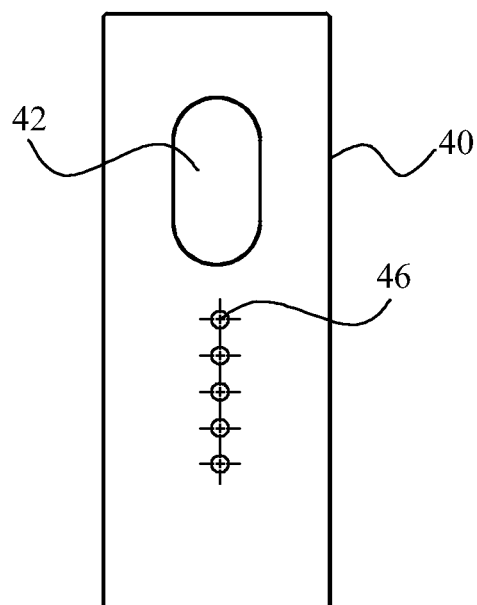


FIG. 10D

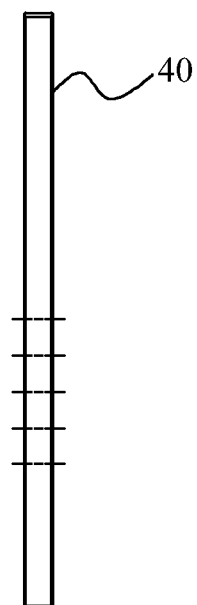


FIG. 11A

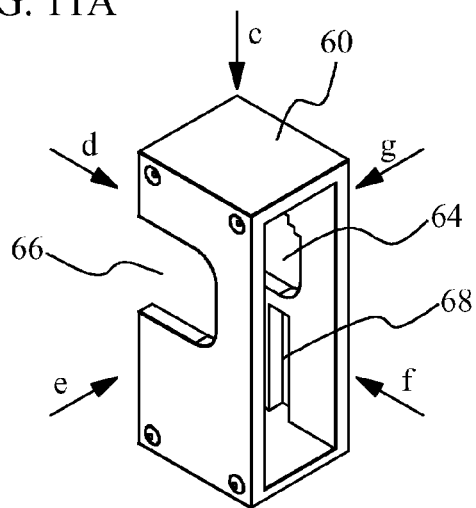


FIG. 11B

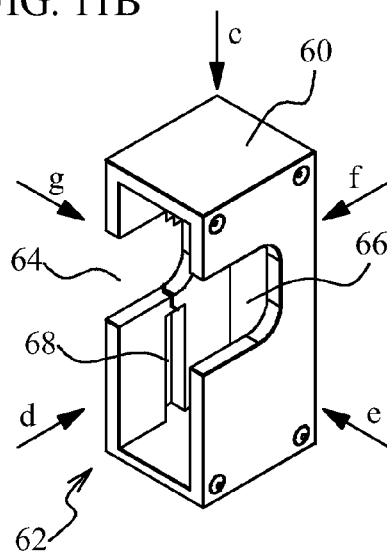


FIG. 11C

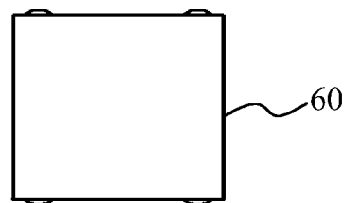


FIG. 11D

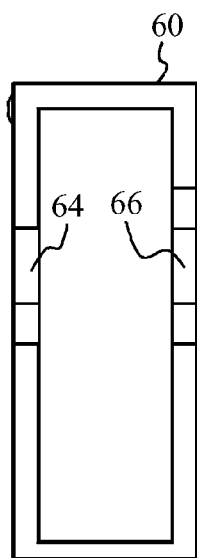


FIG. 11E

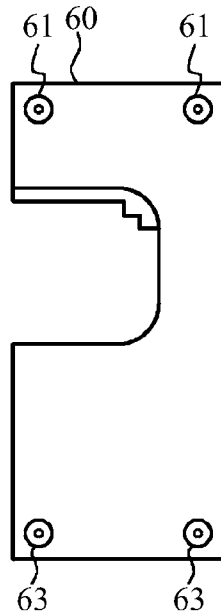


FIG. 11F

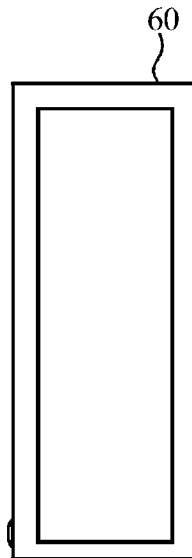


FIG. 11G

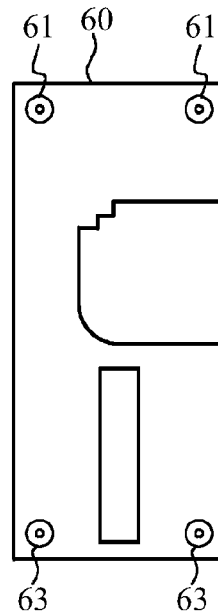


FIG. 12A

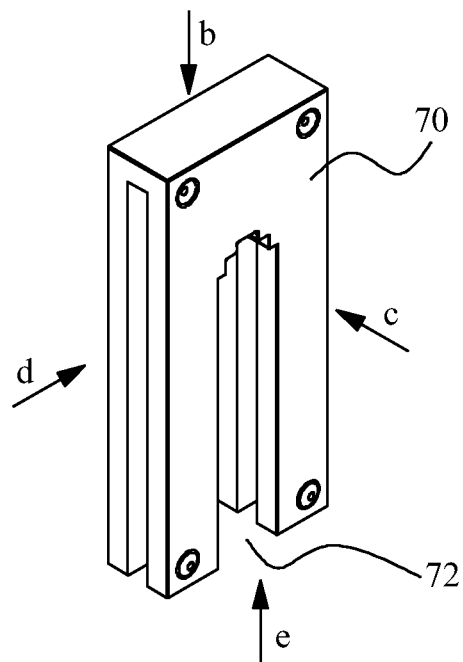


FIG. 12B

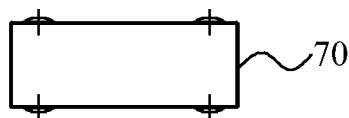


FIG. 12C

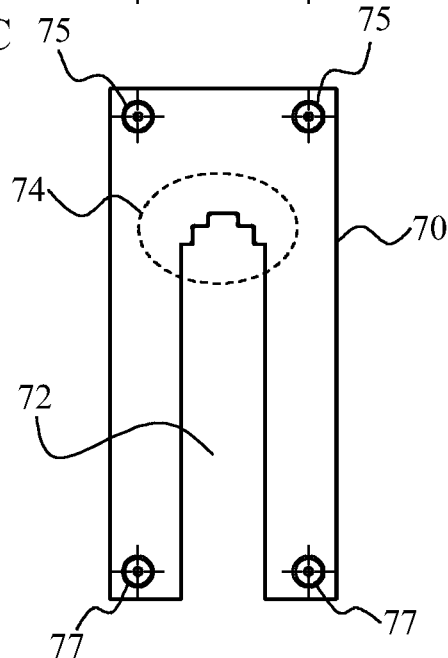


FIG. 12D

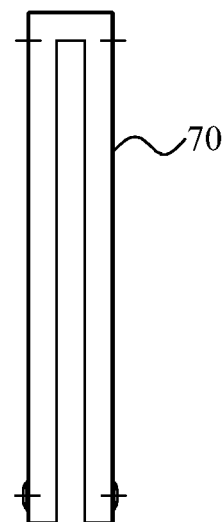


FIG. 12E

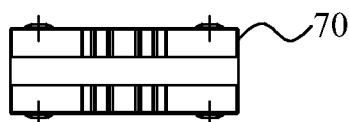


FIG. 13A

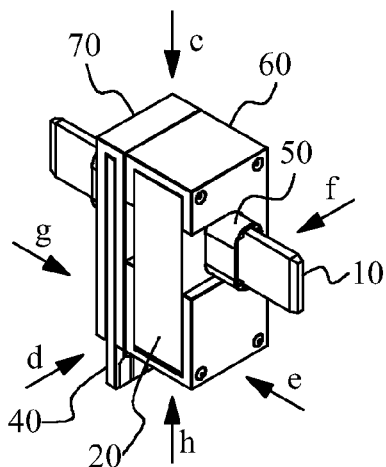


FIG. 13B

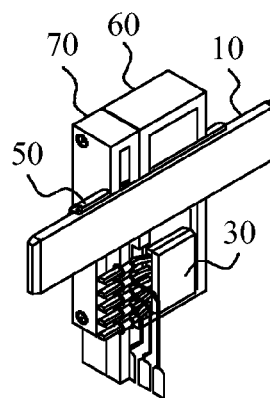


FIG. 13C

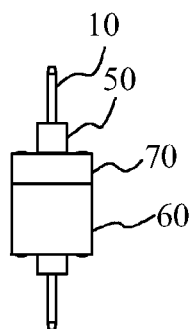


FIG. 13D

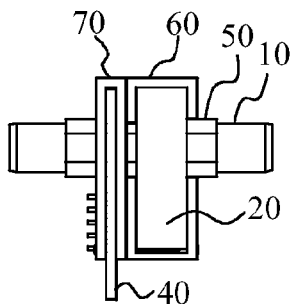


FIG. 13E

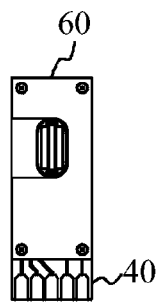


FIG. 13F

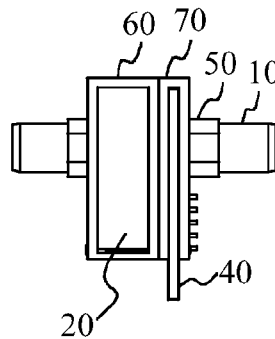


FIG. 13G

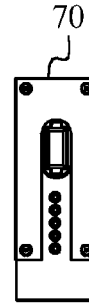


FIG. 13H

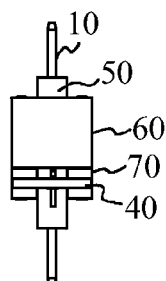


FIG. 14A

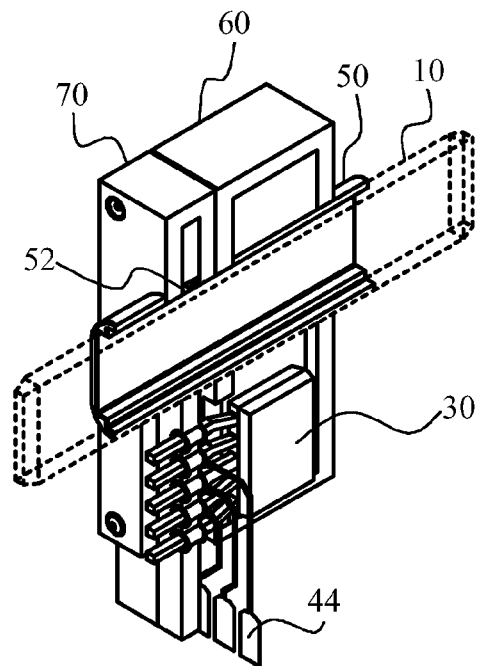


FIG. 14B

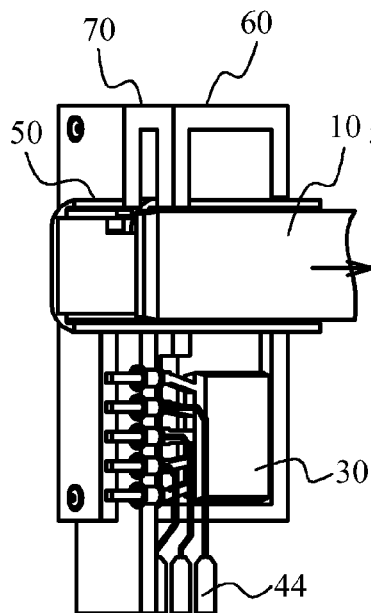


FIG. 14C

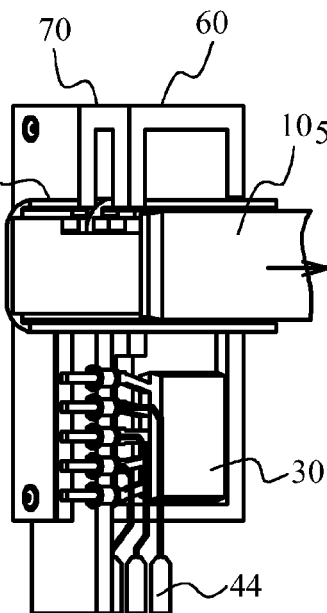


FIG. 14D

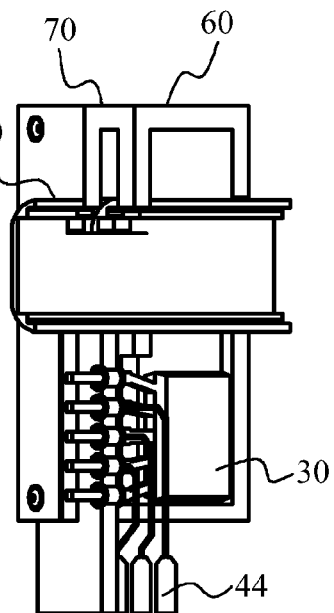


FIG. 15A

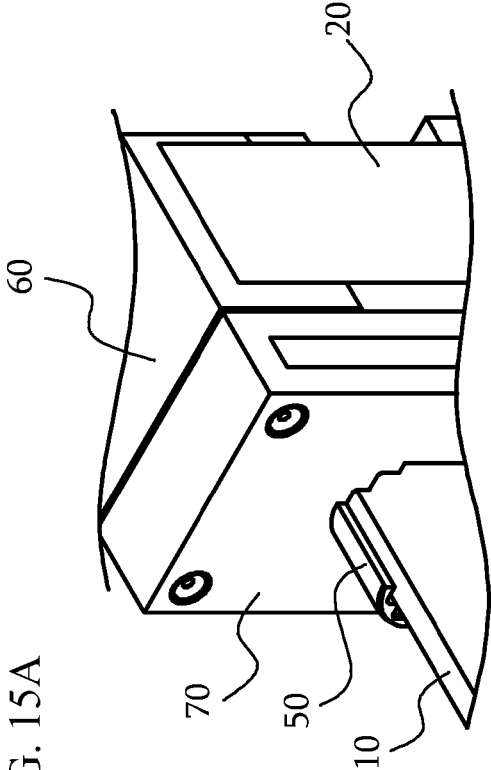


FIG. 15B

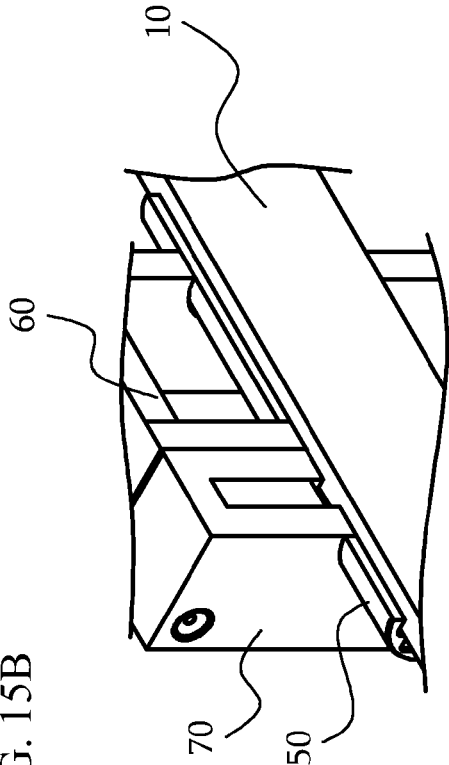


FIG. 15C

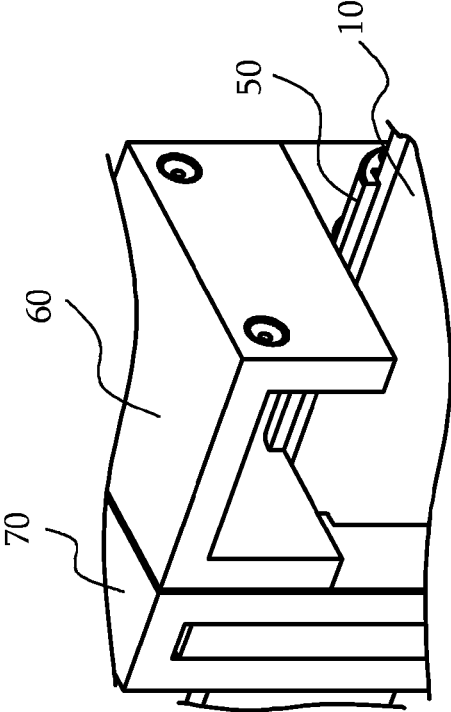


FIG. 15D

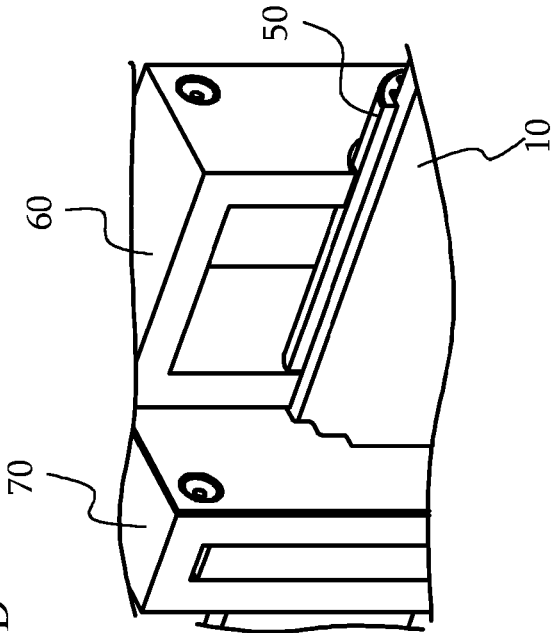


FIG. 16A

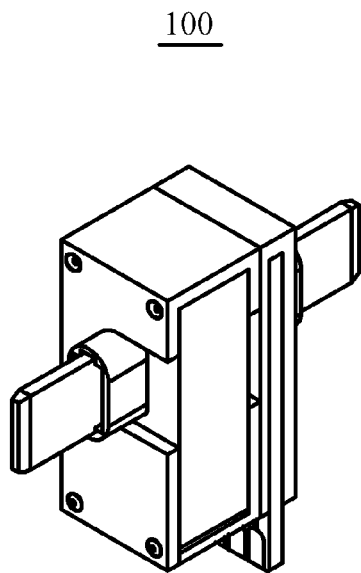


FIG. 16B

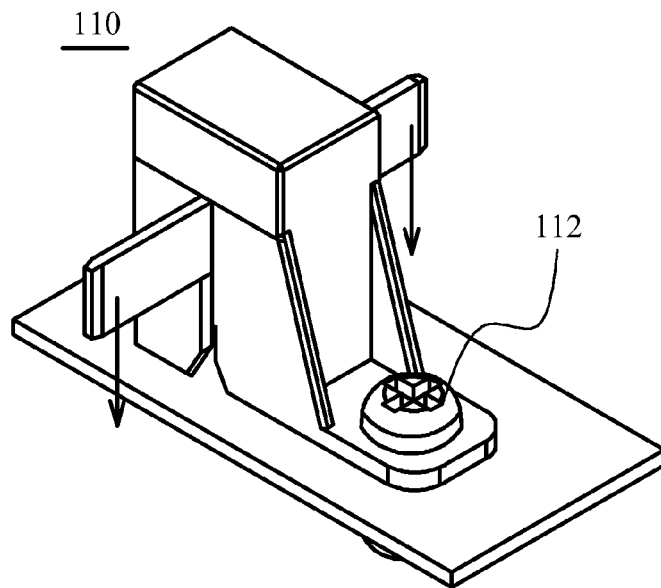


FIG. 17A

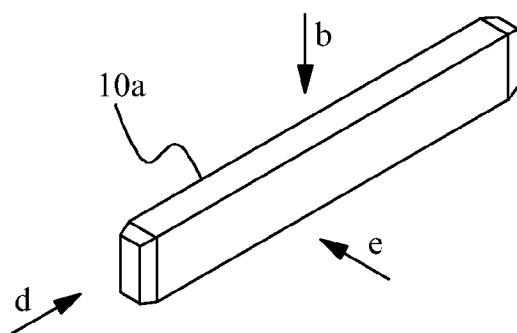


FIG. 17B

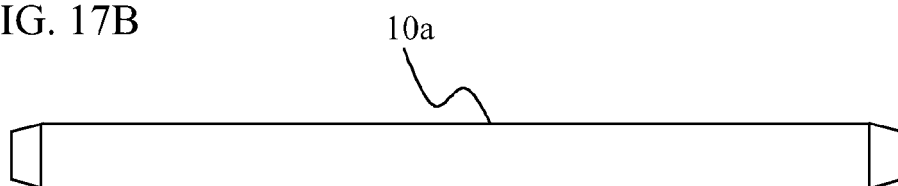


FIG. 17C

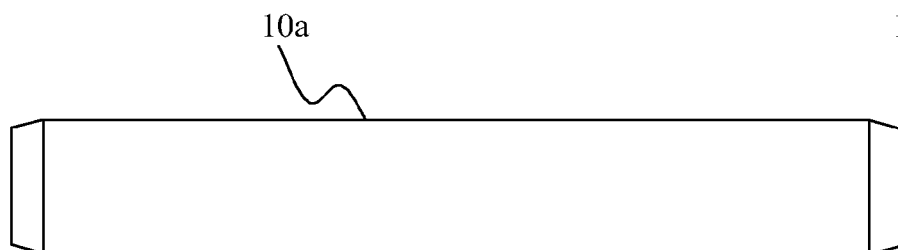


FIG. 17D

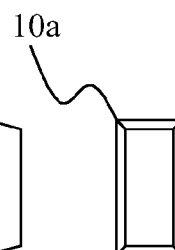


FIG. 18A

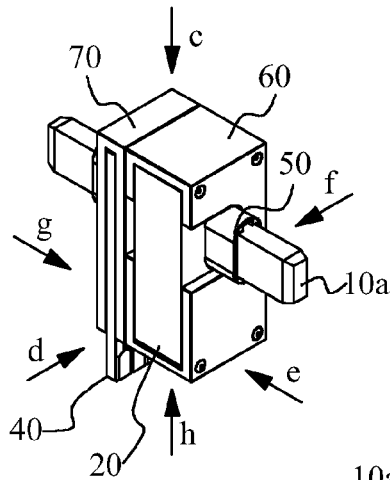


FIG. 18B

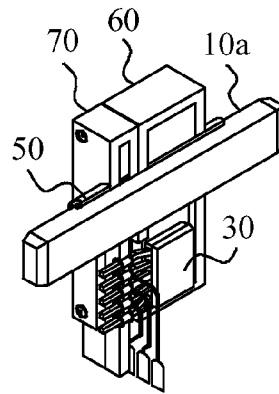


FIG. 18C

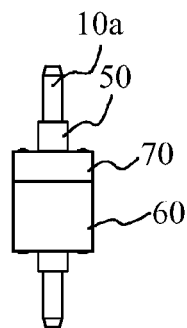


FIG. 18D

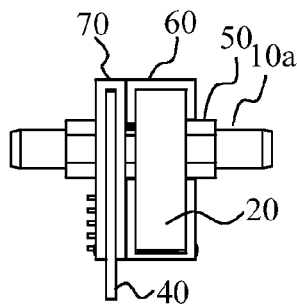


FIG. 18E

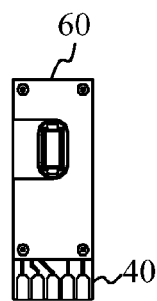


FIG. 18F

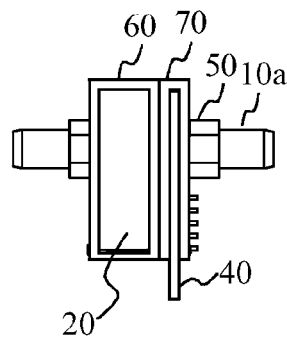


FIG. 18G

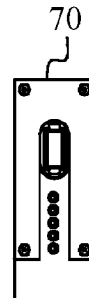


FIG. 18H

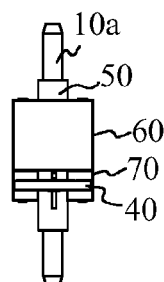


FIG. 19A

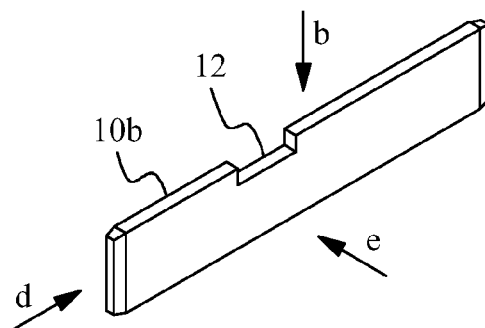


FIG. 19B

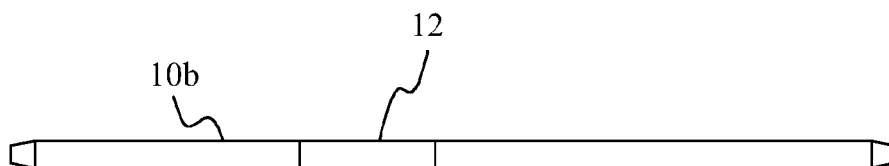


FIG. 19C

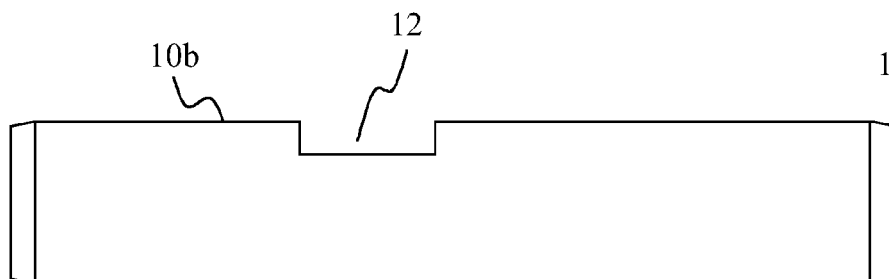


FIG. 19D

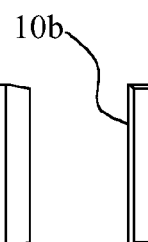


FIG. 20

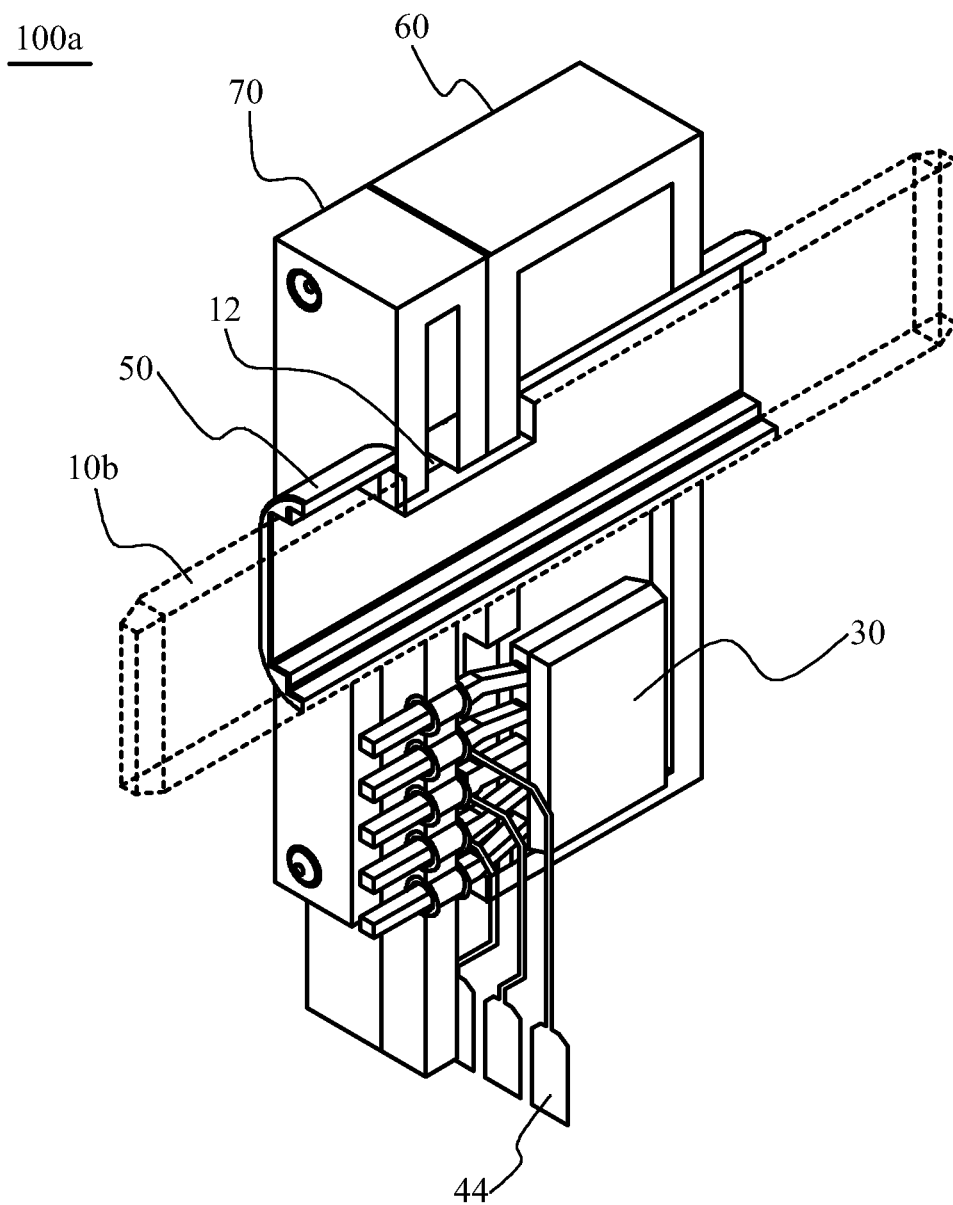


FIG. 21A

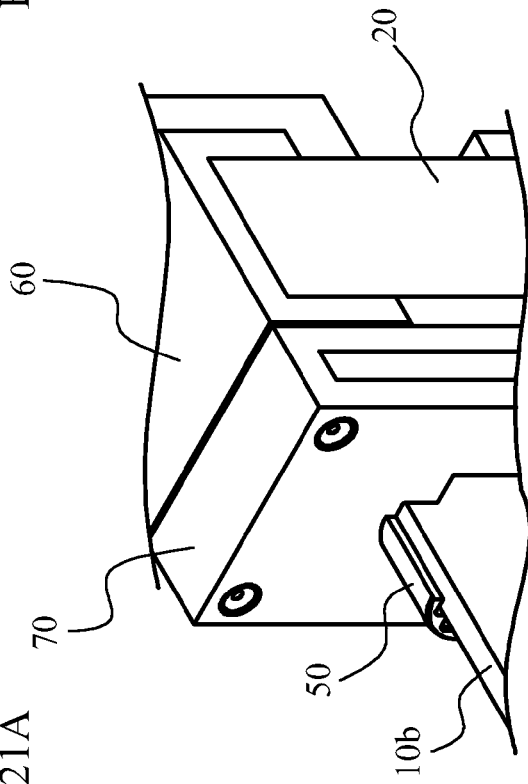


FIG. 21B

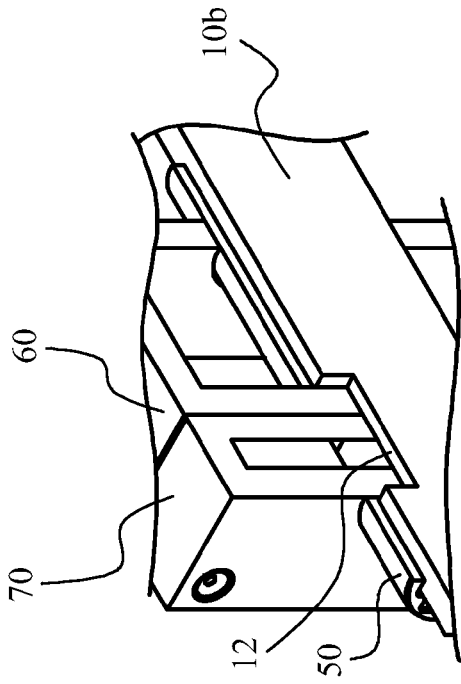


FIG. 21C

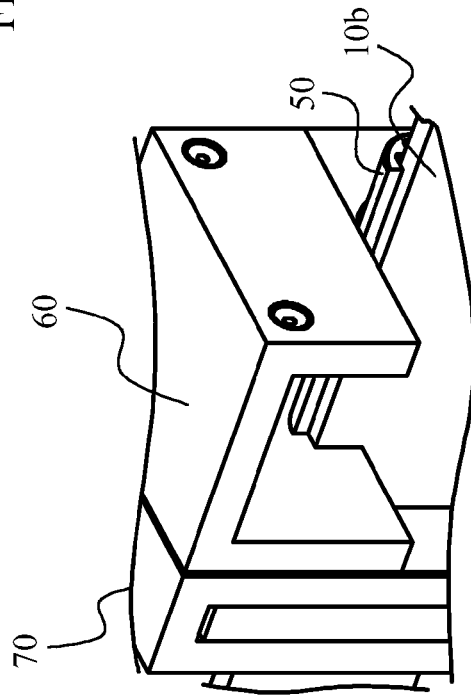


FIG. 21D

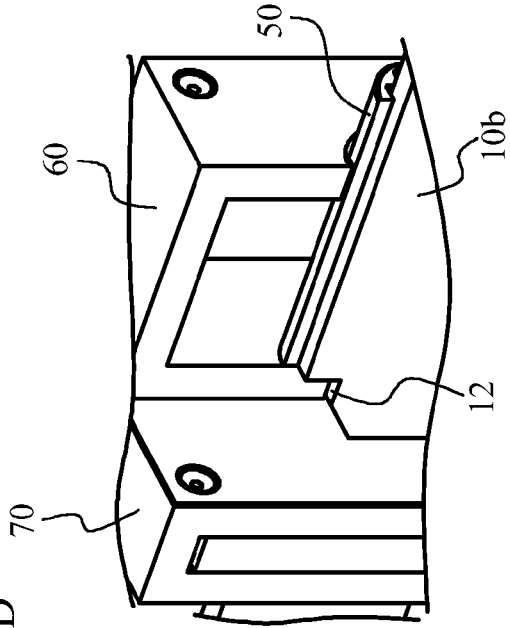


FIG. 22A

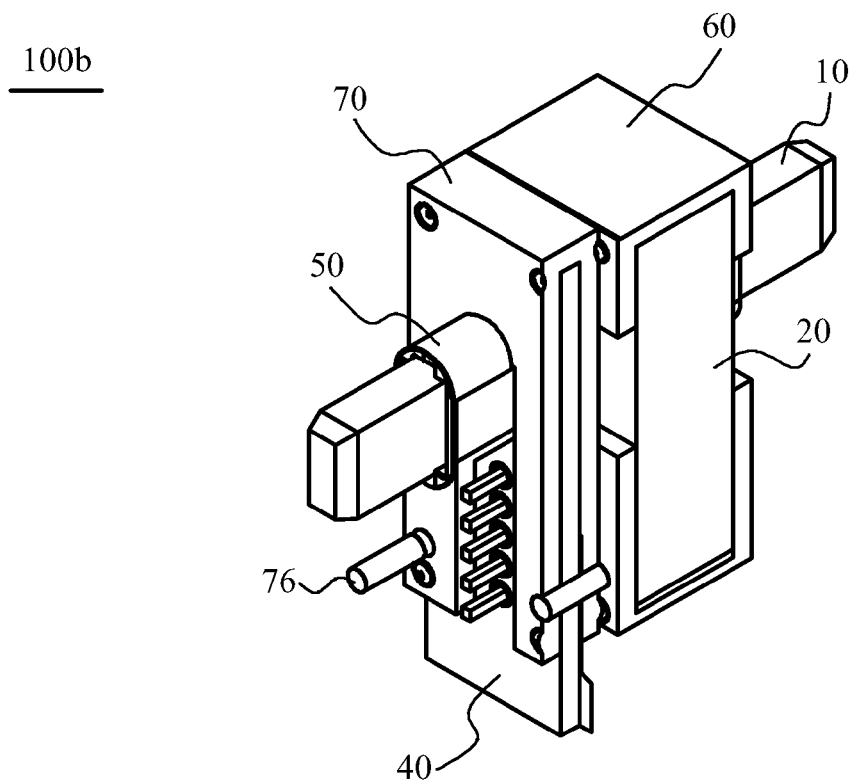


FIG. 22B

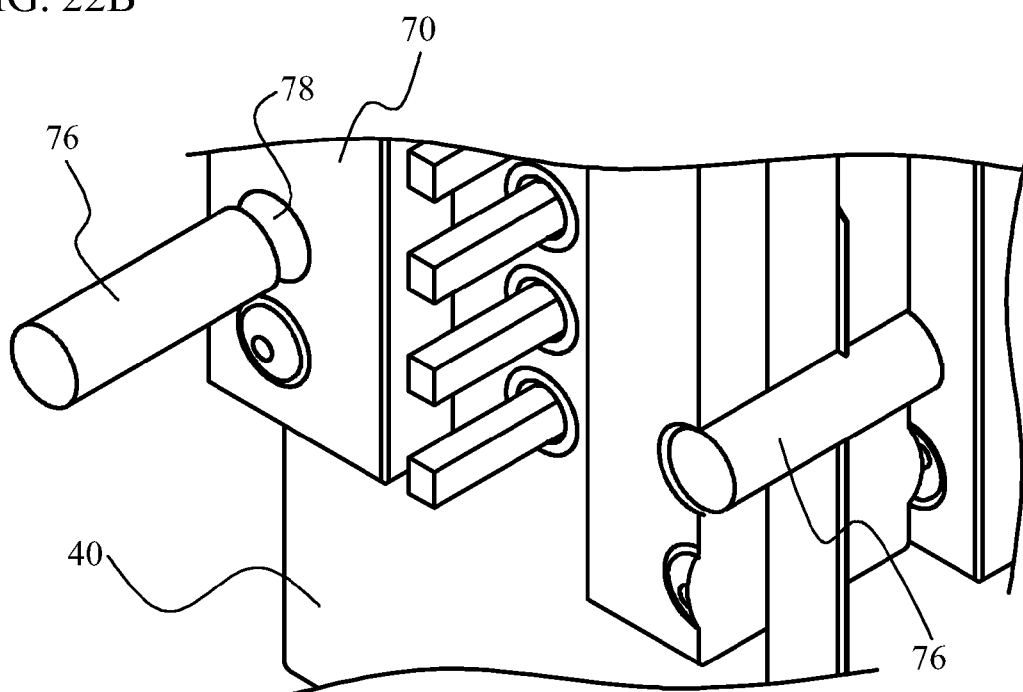


FIG. 23A

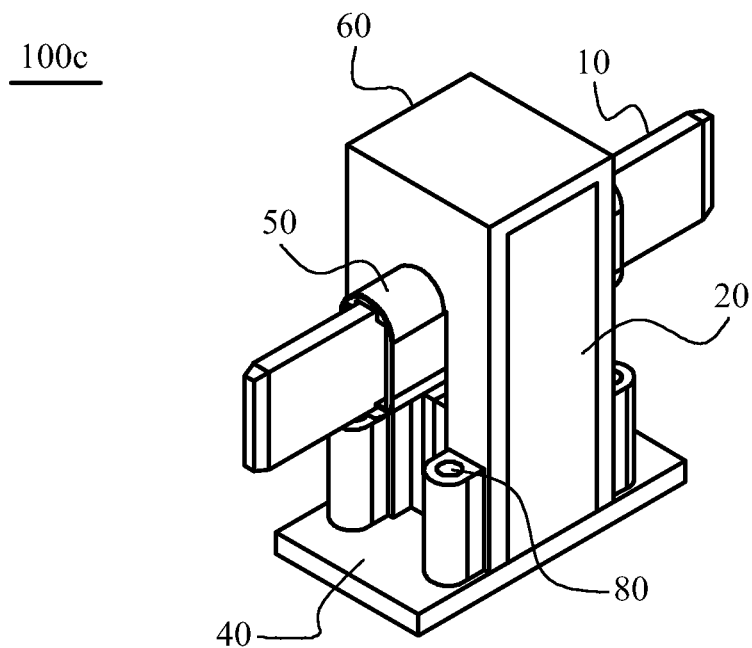


FIG. 23B

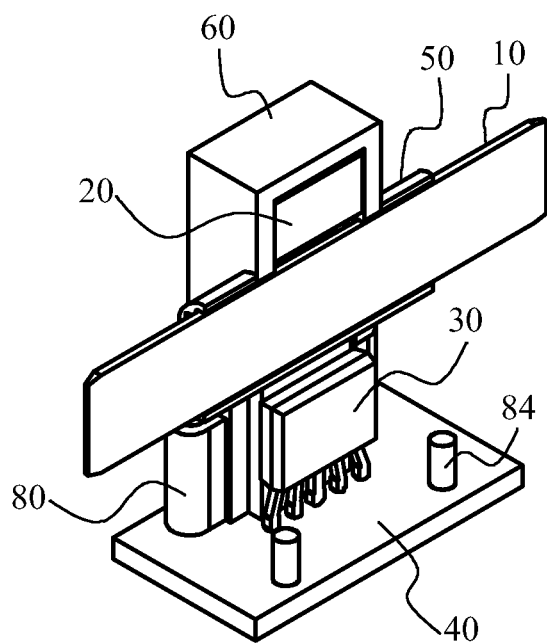


FIG. 23C

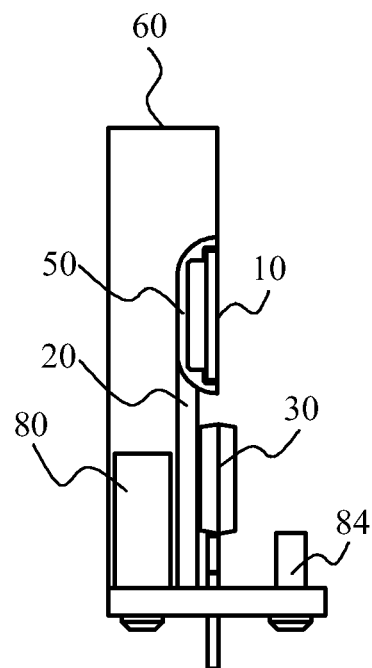


FIG. 24A

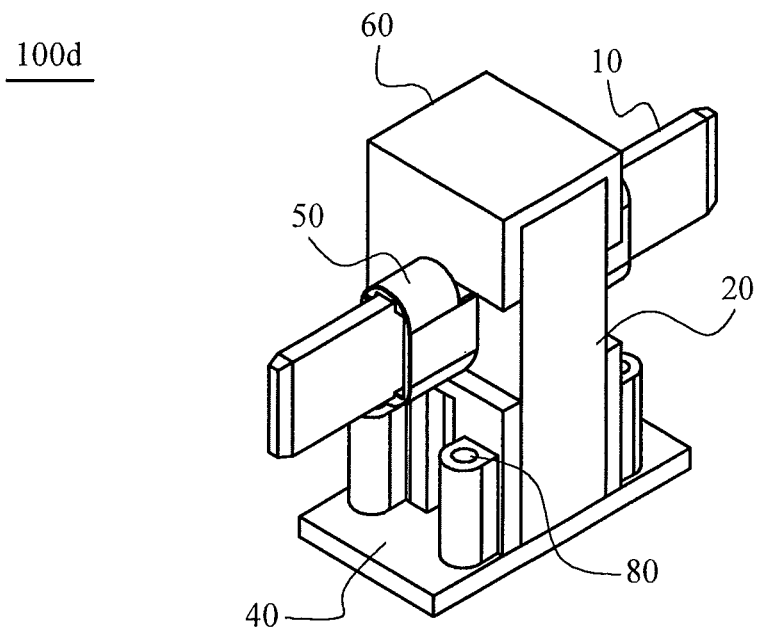


FIG. 24B

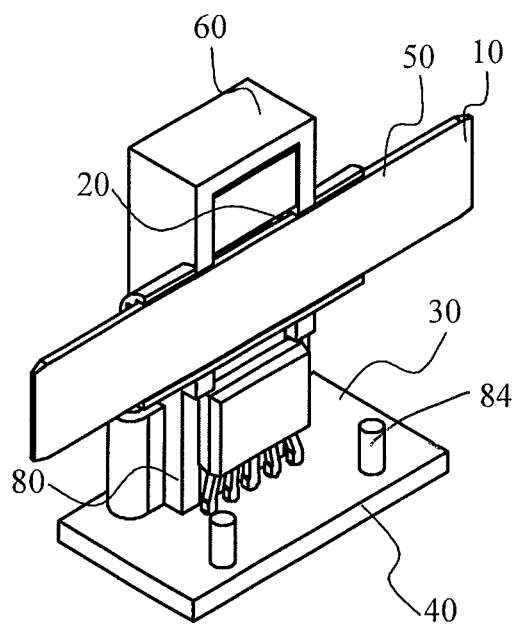


FIG. 24C

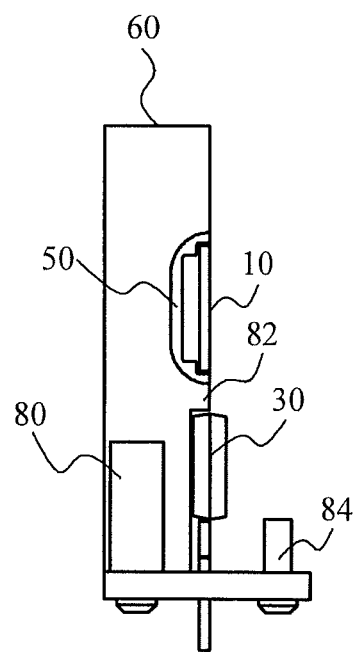


FIG. 25A

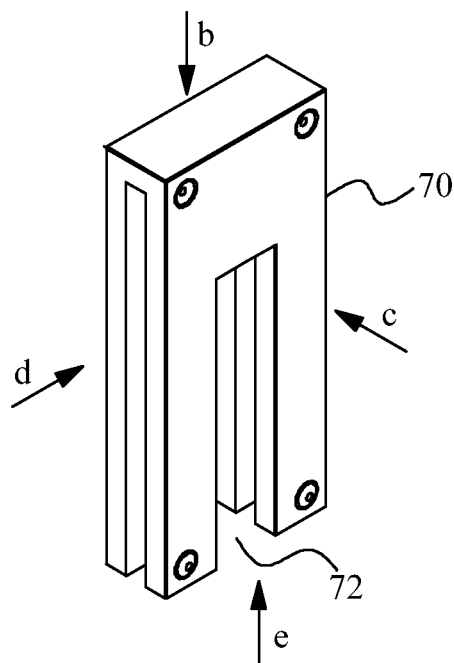


FIG. 25B

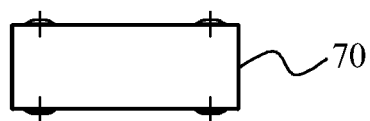


FIG. 25C

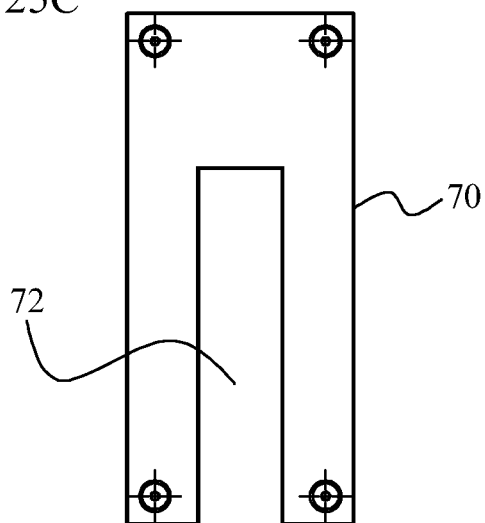


FIG. 25D

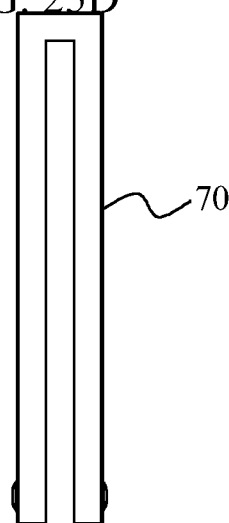
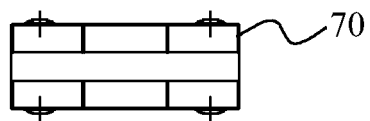


FIG. 25E



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CURRENT SENSOR**CROSS-REFERENCE TO RELATED APPLICATION**

This application is based upon and claims the benefit of priority of the prior Japanese Patent Application No. 2012-206661, filed on Sep. 20, 2012, the entire contents of which are incorporated herein by reference.

FIELD

A certain aspect of the embodiments discussed herein is related to a current sensor.

BACKGROUND

There has been known a power sensor including a bus bar through which a current flows and a Hall element for measuring a magnetic field, a part of the bus bar being covered with ferrite, and the Hall element being located in a gap of the ferrite as disclosed in Japanese Patent Application Publication No. 2011-017618. Such a current sensor requires the bus bar, the ferrite, and the Hall element to have a fixed (stable) positional relationship. For example, the positional relationship may be fixed by a ferrite cover including a slit corresponding to a width of the bus bar.

Conventional current sensors have a difficulty in reducing a space because a device to which the current sensor is installed needs to have a structure for preventing a fall of the bus bar and a structure for screwing the ferrite cover.

SUMMARY

According to an aspect of the present invention, there is provided a current sensor including: a first cover that covers the current bar and includes a cutout portion formed in at least a part thereof; a magnetic substance core that covers at least parts of the current bar and the first cover and includes a gap; a magnetic field measuring element located in the gap; and a second cover that covers the magnetic substance core and the magnetic field measuring element and at least parts of the current bar and the first cover, and is located so that a side surface thereof engages with the cutout portion of the first cover.

The object and advantages of the invention will be realized and attained by the elements and combinations particularly pointed out in the claims.

It is to be understood that both the foregoing general description and the following detailed description are exemplary and explanatory and are not restrictive of the invention, as claimed.

BRIEF DESCRIPTION OF DRAWINGS

FIGS. 1A and 1B are diagrams illustrating a principle of a current sensor;

FIGS. 2A and 2B are diagrams illustrating a structure of a current sensor in accordance with a comparative example;

FIGS. 3A and 3B are diagrams illustrating a method for assembling a current sensor in accordance with a first embodiment (No. 1);

FIGS. 4A and 4B are diagrams illustrating the method for assembling the current sensor in accordance with the first embodiment (No. 2);

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FIGS. 5A and 5B are diagrams illustrating the method for assembling the current sensor in accordance with the first embodiment (No. 3);

FIGS. 6A and 6B are diagrams illustrating the method for assembling the current sensor in accordance with the first embodiment (No. 4);

FIGS. 7A and 7B are diagrams illustrating the method for assembling the current sensor in accordance with the first embodiment (No. 5);

FIGS. 8A through 8D are diagrams illustrating a detailed structure of a bus bar;

FIGS. 9A through 9D are diagrams illustrating a detailed structure of a bus cover;

FIGS. 10A through 10D are diagrams illustrating a detailed structure of a substrate;

FIGS. 11A through 11G are diagrams illustrating a detailed structure of a ferrite cover;

FIGS. 12A through 12E are diagrams illustrating a detailed structure of a substrate cover;

FIGS. 13A through 13H are completion drawings of the current sensor in accordance with the first embodiment;

FIGS. 14A through 14D are diagrams for explaining an engaging state of components (No. 1);

FIGS. 15A through 15D are diagrams for explaining an engaging state of components (No. 2);

FIGS. 16A and 16B are diagrams comparing the current sensor of the first embodiment to the current sensor of the comparative example;

FIGS. 17A through 17D are diagrams illustrating a detailed structure of a bus bar having a different shape;

FIGS. 18A through 18H are completion drawings of a current sensor into which the bus bar with a different shape is inserted;

FIGS. 19A through 19D are diagrams illustrating a structure of a bus bar in accordance with a second embodiment;

FIG. 20 is a diagram illustrating a structure of a current sensor in accordance with the second embodiment;

FIGS. 21A through 21D are diagrams for explaining an engaging state of components;

FIGS. 22A and 22B are diagrams illustrating a structure of a current sensor in accordance with a third embodiment;

FIGS. 23A through 23C are diagrams illustrating a structure of a current sensor in accordance with a fourth embodiment;

FIGS. 24A through 24C are diagrams illustrating a structure of a current sensor in accordance with a variation of the fourth embodiment; and

FIGS. 25A through 25E are diagrams illustrating a variation of the substrate cover.

DESCRIPTION OF EMBODIMENTS

A description will first be given of a principle of a current sensor and a comparative example.

FIGS. 1A and 1B are diagrams illustrating a principle of current sensors in accordance with a comparative example and first through fourth embodiments. FIG. 1A is a perspective view, and FIG. 1B is a plan view viewing FIG. 1A from a penetration direction of a bus bar 10.

As illustrated in FIG. 1A, a current sensor 100 includes the bus bar 10, ferrite 20, a Hall element 30, and a substrate 40. The bus bar 10 is an exemplary current bar through which a measured current flows, and has an elongated plate-like shape. The ferrite 20 is an exemplary magnetic substance core that enhances a magnetic field generated by a current flowing through the bus bar 10. The Hall element 30 is an exemplary magnetic field measuring element for measuring the mag-

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netic field enhanced by the ferrite 20, and is fixed to the substrate 40. The substrate 40 includes wirings (not illustrated), and the wirings are electrically coupled to the Hall element 30. A measuring circuit (not illustrated) for measuring an output signal of the Hall element is located at ends of the wirings formed on the substrate 40, and thus, the current flowing through the bus bar 10 can be detected based on the output.

The ferrite 20 is shaped in such a manner that side surfaces of a cuboid are hollowed out through an opposite side to be keyhole-shaped as illustrated in FIG. 1A, for example. In the following description, a center portion (base portion of the keyhole) in the above described hollow is described as a hole portion 22, and a slit portion heading from the hole portion 22 to a bottom surface (tip portion of the keyhole) is described as a gap 24. As illustrated in FIG. 1B, the bus bar 10 is located so as to penetrate the hole portion 22, and the Hall element 30 is located in the gap 24. The ferrite 20 has only to have a shape covering a part of the bus bar 10 in an extending direction, and the shape thereof is not limited to the tangible shape illustrated to FIG. 1.

To perform correct measurement with the sensor, the bus bar 10, the ferrite 20, and the Hall element 30 preferably have a fixed positional relationship. Especially, if the bus bar 10 comes in contact with the ferrite 20, the current flowing through the bus bar 10 causes a danger such as an electric shock and thus, they are preferably located away from each other as illustrated in FIG. 1B.

The positional relationship can be fixed by filling up a clearance between the bus bar 10 and the ferrite 20 with a liquid such as an adhesive, but the cost for drying treatment till the liquid is solidified is high, and thus this method is not preferable. Moreover, a bus cover including a slit having the practically same width as that of the bus bar 10 may be placed over the bus bar 10 and the ferrite 20 and fixed to the substrate 40 (see FIGS. 16A and 16B). However, this method requires the substrate 40 to have a structure (e.g. a screw clamp, a nail, or the like) for fixing the positional relationship, and thus the positional relationship cannot be fixed with the current sensor 100 alone. Therefore, a structure presented by the comparative example (FIGS. 2A and 2B) will be considered.

FIGS. 2A and 2B are diagrams illustrating a structure of a ferrite portion of a current sensor in accordance with the comparative example. FIG. 2A illustrates a bus cover, and FIG. 2B is a diagram illustrating a state where the bus bar 10 with the bus cover is installed in the ferrite 20. As illustrated in FIG. 2A, a bus cover 50 includes a cavity corresponding to the bus bar 10 formed in the inside thereof, and has a tubular shape as a whole. As illustrated in FIG. 2B, the bus cover 50 with the bus bar 10 penetrating therethrough is inserted into the hole portion of the ferrite 20, and thereby, prevents contact between the ferrite 20 and the bus bar 10 and can protect a user from electrocution. This method can be achieved only by covering the bus bar 10 with the bus cover 50, and thus the positional relationship can be fixed by the current sensor 100 alone.

However, the method in accordance with the comparative example has a possibility that the bus cover 50 falls down from the ferrite 20. Thus, a detailed description will be given of a structure of current sensors capable of stabilizing a positional relationship among the bus bar 10, the ferrite 20, and the Hall element 30 in the following embodiments.

[First Embodiment]

First, a description will be given of a method for assembling the current sensor 100 in accordance with a first embodiment based on FIG. 3A through FIG. 7B. Then, a description will be given of a detail of each component con-

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stituting the current sensor 100 based on FIG. 8A through FIG. 12E, and finally a description will be given of a detailed structure of the current sensor 100 based on FIG. 14A through FIG. 16B.

FIG. 3A through FIG. 7B are perspective views illustrating the method for assembling the current sensor 100 of the first embodiment. As illustrated in FIG. 3A, prepared is the bus cover 50 that is an exemplary first cover. Unlike the comparative example, the bus cover 50 of the first embodiment includes a cutout portion 52 in an upper surface thereof. The cutout portion 52 is formed by removing a part of the bus cover 50, and the inside of the bus cover 50 is exposed from the cutout portion 52. The cutout portion 52 is a structure for engaging with (hanging) side surfaces of a ferrite cover and a substrate cover as described later.

Then, the bus bar 10 is passed through the bus cover 50, and the bus cover 50 with the bus bar 10 is passed through the hole portion 22 of the ferrite 20 as illustrated in FIG. 3B. At this point, as the bus bar 10 is exposed to an outside from the cutout portion 52, the bus cover 50 is located so that the cutout portion 52 is positioned outside the ferrite 20 to prevent the bus bar 10 from contacting the ferrite 20.

Then, a ferrite cover 60 is placed to cover the ferrite 20 as illustrated in FIG. 4A and FIG. 4B. The ferrite cover 60 is an exemplary second cover that protects the ferrite 20, but also has a function for fixing the positional relationship among the bus bar 10, the bus cover 50, and the ferrite 20 in the present embodiment. One of side surfaces of the ferrite cover 60 is an opening portion 62, and the whole of the ferrite 20 is housed inside the ferrite cover 60 from the opening portion 62. Further, recess portions 64 and 66 are formed in two side surfaces adjacent to the opening portion 62 (i.e. two side surfaces penetrated by the bus bar 10), and the bus bar 10 and the bus cover 50 are placed in the recess portions 64 and 66. In addition, a slit 68 into which the Hall element 30 is inserted in a process described later is formed in one of the side surfaces penetrated by the bus bar 10.

Then, the substrate 40 is mounted on to the bus bar 10 as illustrated in FIG. 5A and FIG. 5B. A penetration hole 42 larger than the cross-section of the bus cover 50 is formed in the substrate 40. The bus cover 50 and the bus bar 10 are passed through the penetration hole 42, and thereby the substrate 40 is hung on the cutout portion 52 of the bus cover 50 (i.e. bus bar 10) and tentatively positioned. Moreover, wirings 44 are formed on the substrate 40, and the Hall element 30 electrically coupled to the wirings 44 is fixed to the substrate 40. The Hall element 30 protrudes from the surface of the substrate 40, and is inserted from the slit 68 of the ferrite cover 60 into the inside and positioned in the gap 24 of the ferrite 20 when the substrate 40 is hung on the bus bar 10.

Then as illustrated in FIGS. 6A and 6B, a substrate cover 70 is placed to cover the substrate 40. Unlike the ferrite cover 60, the substrate cover 70 is mounted on to the substrate 40 from an upper direction (direction counter to gravity). At this point, a side surface of the substrate cover 70 engages with the cutout portion 52 of the bus cover 50. Moreover, side surfaces of the ferrite cover 60 and the substrate cover 70 contact each other and a raised structure and a recess structure formed in the side surfaces engage with each other, and thereby, the ferrite cover 60 and the substrate cover 70 are fixed to each other. This will be described in detail later.

FIG. 7A and FIG. 7B are perspective views of the current sensor 100 to which the substrate cover 70 is mounted on. The cutout portion 52 of the bus cover 50 has a length (length in a direction in which the bus bar 10 extends) configured to be equal to the sum of the overall thickness of the substrate cover 70 and the thickness of one of the side surfaces of the ferrite

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cover 60. This configuration allows the ferrite cover 60 and the substrate cover 70 to be engaged with and fixed to the cutout portion 52 of the bus cover 50.

FIGS. 8A through 8D are diagrams illustrating a detailed structure of the bus bar 10. FIG. 8A is a perspective view, and FIGS. 8B through 8D are plan views viewed from b through d-directions in FIG. 8A respectively. As illustrated, the bus bar 10 has an elongated plate-like shape in one direction (d-direction). As illustrated in FIGS. 8B through 8D, both end portions of the bus bar 10 are inclined so that the cross-sections thereof decrease toward the outside. The structure of the bus bar 10 is not limited to the present embodiment, and may be any that allows a measured current to flow there-through.

FIGS. 9A through 9D are diagrams illustrating a detailed structure of the bus cover 50. FIG. 9A is a perspective view, and FIGS. 9B through 9D are plan views viewed from b through d-directions in FIG. 9A respectively. As illustrated in FIG. 9B, an upper portion of the bus cover 50 is removed to the cutout portion 52, and the inside of the bus cover 50 is exposed, but the structure of the cutout portion 52 is not limited to the present embodiment and may be any that can engage with the ferrite cover 60 and the substrate cover 70. In addition, as illustrated in FIG. 9D, the cavity formed in the bus cover 50 into which the bus bar 10 is inserted has a nearly cross shape formed by crossing two rectangles with different shapes at centers thereof. This configuration is for allowing the bus bars 10 with different sizes to be inserted, and this will be described in detail later.

FIG. 10 is a diagram illustrating a detailed structure of the substrate 40. FIG. 10A is a perspective view, and FIGS. 10B through 10D are plan views viewed from b through d-directions in FIG. 10A respectively. FIGS. 10A through 10D omit the illustration of the Hall element 30 and the wirings 44. As illustrated in FIGS. 10A and 10C, the substrate 40 includes: the penetration hole 42 into which the bus bar 10 and the bus cover 50 are inserted; and pin holes 46 to which pins of the Hall element 30 are inserted. The Hall element 30 is fixed to the substrate 40 by inserting the pins to the pin holes 46 and penetrating them through the opposite side.

FIGS. 11A through 11G are diagrams illustrating a detailed structure of the ferrite cover 60. FIG. 11A and FIG. 11B are perspective views viewed from different directions, and FIG. 11C through FIG. 11D are plan views viewed from c through g-directions in the perspective views respectively. As illustrated, the side surface in the d-direction of the ferrite cover 60 is the opening portion 62 from which the ferrite 20 is inserted. The side surfaces in the e-direction and the g-direction of the ferrite cover 60 include the recess portions 64 and 66 communicating with the opening portion 62, respectively. The recess portion 64 formed in the side surface in the g-direction engages with the cutout portion 52 of the bus cover 50, and thus is smaller than the recess portion 66 formed in the side surface in the e-direction, and a corner portion thereof is not rounded so as to make the engagement easy. In contrast, the recess portion formed in the side surface in the e-direction does not engage with the cutout portion 52 of the bus cover 50, and thus is larger than the recess portion 64 formed in the side surface in the g-direction, and corner portions are rounded so as to be along the chassis of the bus cover 50. These configurations are illustrated in FIG. 11D, FIG. 11E, and FIG. 11G.

Moreover, recess and raised structures that engage with the substrate cover 70 are formed in the ferrite cover 60. The present embodiment forms recess structures 61 at an upper side (side closer to the bus bar 10) and raised structures 63 at a lower side, but does not intend to suggest any limitation. Moreover, the side surface in the f-direction of the ferrite

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cover 60 is an opening portion as with the side surface in the d-direction in the present embodiment, but the ferrite cover 60 has only to cover the ferrite 20 from at least the d-direction or the f-direction, and the other opening portion may be closed.

FIGS. 12A through 12E are diagrams illustrating a detailed structure of the substrate cover 70. FIG. 12A is a perspective view, and FIGS. 12B through 12E are plan views viewed from b through e-directions in FIG. 12A respectively. As illustrated, two side surfaces of the substrate cover 70 (c-direction and counter direction thereof) include recess portions 72 formed therein so as to open toward the bottom side (e-direction). A cross-sectional shape of the base portion of the recess portion 72 is a step-like shape as indicated by reference numeral 74 in FIG. 12C. This is for engaging with a multilevel structure formed by the bus bar 10 exposed from the cutout portion 52 and the chassis of the bus cover 50 in the cutout portion 52 of the bus cover 50. This structure allows the substrate cover 70 to stably support the bus cover 50.

In addition, recess and raised structures for engaging with the ferrite cover 60 are formed in the substrate cover 70. The present embodiment forms raised structures 75 at an upper side (side closer to the bus bar 10) so as to engage with the ferrite cover 60 of FIGS. 11A through 11G, and forms recess structures 77 at a lower side, but does not intend to suggest any limitation.

FIGS. 13A through 13H are diagrams illustrating a detailed structure of a completion state of the current sensor 100. FIG. 13A is an external perspective view, and FIG. 13B is a perspective view in which the current sensor 100 is halved lengthwise. FIGS. 13C through 13H are plan views viewed from c through h-direction in FIG. 13A respectively. As illustrated, the bus bar 10 is inserted into the inside of the bus cover 50 to be positioned with respect to the ferrite 20. Especially, in the inside of the ferrite cover 60, the bus cover 50 separates the bus bar 10 from the ferrite 20, and prevents contact therebetween. Moreover, the Hall element 30 electrically coupled to the substrate 40 is inserted from the slit 68 of the ferrite cover 60 into the gap 24 of the ferrite 20, and positioned with respect to the ferrite 20. An engaging state of the bus cover 50, the ferrite cover 60, and the substrate cover 70 will be described in detail in FIG. 14A through FIG. 15D.

FIGS. 14A through 14D are diagrams for explaining an engaging state of components in the current sensor 100 (No. 1), and illustrate the current sensor 100 halved lengthwise as with FIG. 13B. As illustrated in FIG. 14A, a first outer periphery of the cutout portion 52 of the bus cover 50 engages with the side surface of the substrate cover 70, and a second outer periphery engages with the side surface of the ferrite cover 60. The bus bar 10 inserted into the bus cover 50 fails to engage with the substrate cover 70 and the ferrite cover 60, and thus can be freely moved along its extending direction (insertion direction) as illustrated in FIGS. 14B through 14D. Therefore, in an assembly process, the components except the bus bar 10 are assembled first, and the bus bar 10 can be inserted lastly.

FIGS. 15A through 15D are diagrams for explaining the engaging state of the components in the current sensor 100 (No. 2), and enlarge an engaging part illustrated in FIGS. 14A through 14D. As illustrated in FIG. 15A, the step-like shape of the recess portion 72 of the substrate cover 70 engages with the multilevel structure of the cutout portion 52 formed by the bus bar 10 and the bus cover 50. In addition, as illustrated in FIGS. 15B and 15D, the side surface of the ferrite cover 60 located on the opposite side to the substrate cover 70 does not engage with the cutout portion 52 of the bus cover 50, and contacts the bus cover 50 along the roundness of the bus cover 50.

As described above, the current sensor **100** of the first embodiment engages the ferrite cover **60** with the cutout portion **52** of the bus cover **50** to fix the ferrite cover **60** and the bus cover **50**. In addition, the bus bar **10** and the ferrite **20** are positioned by the ferrite cover **60** and the bus cover **50**. Therefore, the positional relationship among the components of the current sensor can be stabilized.

Moreover, the current sensor **100** of the first embodiment places the substrate **40** on which the Hall element **30** is mounted to be aligned with the ferrite **20** from the lateral direction of the ferrite cover **60**, and positions and fixes the substrate **40** by the substrate cover **70**. This can reduce the space compared to a case where the bottom portion of the ferrite **20** is fixed and screwed on the substrate.

FIGS. **16A** and **16B** are perspective views comparing the current sensors of the first embodiment and a comparative example (different from the one illustrated in FIG. **2**). As illustrated, the first embodiment (FIG. **16A**) reduces an installation space for the current sensor **100** compared to the current sensor **110** of the comparative example (FIG. **16B**) because a structure supporting a fall of the bus bar **10** and a screw clamp receiving a screw **112** are unnecessary. More specifically, the installation area can be reduced by approximately 60%.

Further, the current sensor **100** of the first embodiment is configured so that only one side surface of the two side surfaces of the ferrite cover **60** penetrated by the bus bar **10** engages with the cutout portion **52** of the bus cover **50**. This configuration allows the bus cover **50** to separate the ferrite **20** from the bus bar **10** in the inside of the ferrite cover **60**, and prevent contact between them.

In addition, the current sensor of the first embodiment is configured so that the cross sectional shape of the bus cover **50** is a nearly cross shape formed by crossing two different rectangles at their centers, and thus can accommodate two different bus bars **10**. This configuration enables to quickly accommodate the specifications of the various devices because the bus bar **10** can be easily changed when the bus bar **10** is selected from several types thereof in accordance with circumstances.

FIGS. **17A** through **17D** are diagrams illustrating a detailed structure of a bus bar with a different size. FIG. **17A** is a perspective view, and FIGS. **17B** through **17D** are plan views viewed from b through d-direction in FIG. **17A**. The long side of the rectangle in the cross section is short and the short side is long compared to the bus bar illustrated in FIGS. **8A** through **8H**. As a whole, the cross section area is large (bold) and a large amount of current can flow compared to the bus bar in FIGS. **8A** through **8H**.

FIGS. **18A** through **18H** are diagrams illustrating a state where a bus bar **10a** in FIGS. **17A** through **17D** is inserted into the current sensor **100**, and correspond to FIGS. **13A** through **13H**. FIG. **18A** is an external perspective view, FIG. **18B** is a perspective view in which the current sensor **100** is halved lengthwise. FIGS. **18C** through **18H** are plan views viewed from c through h-direction in FIG. **18A** respectively. The same bus cover **50** is used in FIGS. **13A** through **13H** and FIGS. **18A** through **18H**, and only the shape of the bus bar is different, but the positional relationship between the bus bar **10a** and the ferrite **20** is stable as with the FIGS. **13A** through **13H**.

Moreover, the current sensor **100** of the first embodiment forms a recess structure and a raised structure engaging with each other in the side surfaces of the ferrite cover **60** and the substrate cover **70**. This configuration allows the ferrite cover **60** to directly engage with the substrate cover **70**, and can achieve further stabilization. The tangible structure of the

recess and raised structures is not limited to the one described in the first embodiment. For example, the recess structure and the raised structure may be formed in any of the ferrite cover **60** and the substrate cover **70**, or may be formed in both. The number of and the formation position of the recess structure and the raised structure are not limited either.

[Second Embodiment]

A second embodiment engages not only a bus cover but also a bus bar with a ferrite cover.

FIGS. **19A** through **19D** are diagrams illustrating a detailed structure of a bus bar **10b** in accordance with the second embodiment. FIG. **19A** is a perspective view, and FIGS. **19B** through **19D** are plan views viewed from b through d-direction in FIG. **19A**. As illustrated in FIG. **19A** and FIG. **19C**, an upper edge (edge in the b-direction) of the bus bar **10b** includes a recess portion **12** formed in a position corresponding to the cutout portion **52** of the bus cover **50**. A shape of the recess portion **12** may be any that can engage with ferrite cover **60** and the substrate cover **70**, and is not limited to the tangible structure illustrated in FIGS. **19A** through **19D**.

FIG. **20** is a completion drawing of a current sensor **100a** in accordance with the second embodiment, and is a perspective view in which the current sensor **100a** is halved lengthwise. An external view of the current sensor **100a** is the same as that of the first embodiment, and the illustration thereof is omitted (the same as FIG. **18A** and FIGS. **18C** through **18H**). As illustrated in FIG. **20**, the substrate cover **70** and the ferrite cover **60** engage with the cutout portion **52** of the bus cover **50** and the recess portion **12** of the bus bar **10b**. Thereby, unlike FIGS. **14B** through **14D** of the first embodiment, the bus bar **10b** cannot move in the insertion direction.

FIGS. **21A** through **21D** are diagrams for explaining an engaging state of components in the current sensor **100a**, and enlarges the engaging part illustrated in FIG. **20**. As illustrated in FIGS. **21A** and **21B**, the side surface at an inner side (substrate cover **70** side) of the ferrite cover **60** engages with the cutout portion **52** of the bus cover **50** and the recess portion **12** of the bus bar **10b**. Moreover, as illustrated in FIGS. **21C** and **21D**, the side surface at an outer side (opposite side to the substrate cover **70**) of the ferrite cover **60** does not engage with the cutout portion **52** of the bus cover **50**, and contacts the bus cover **50** along the roundness of the outer ward of the bus cover **50**.

as described above, the current sensor **100a** of the second embodiment engages the ferrite cover **60** with the recess portion **12** located in the bus bar **10b** to fix the position of the bus bar **10b**, and thereby, can achieve further stabilization.

[Third Embodiment]

A third embodiment achieves further fixation of the substrate cover **70** by pins.

FIG. **22A** is an external perspective view (partly cross-sectional view) of a current sensor **100b** of the third embodiment, and FIG. **22B** is an enlarged view of a pin insertion area. As illustrated in FIG. **22B**, in the current sensor **100b**, penetration holes through which pins **76** penetrate are formed in the substrate **40** and the substrate cover **70** (numeral reference **78** represents the penetration holes of the substrate cover **70**). The pins **76** penetrating through the penetration holes for fixation require detachment of the pins **76** when the current sensor **100b** is deconstructed, and thus the substrate **40** and the substrate cover **70** are further stably fixed. Instead of the pins **76**, a member such as a screw may be used. The member may be any that can fix the substrate **40** and the substrate cover **70** through the penetration holes formed in them, and is not limited to the present embodiment.

[Fourth Embodiment]

A fourth embodiment mounts the substrate **40** on to a bottom of the ferrite **20**.

FIGS. **23A** through **23C** are diagrams illustrating a structure of a current sensor **100c** in accordance with the fourth embodiment. FIG. **23A** is an external perspective view, FIG. **23B** is a cross-sectional view in which the current sensor **100c** is halved lengthwise, and FIG. **23C** is a plan view that views FIG. **23B** from the insertion direction of the bus bar **10**. As illustrated, the Hall element **30** is fixed to the substrate **40** so as to protrude upward, the ferrite **20** and the ferrite cover **60** are placed from the upper direction of the substrate **40**, and thereby, the Hall element **30** is inserted into the gap **24** of the ferrite **20**. As illustrated in FIGS. **23B** and **23C**, the ferrite cover **60** includes a reception portion **80** into which a screw can be inserted from a bottom, and a pin or screw **84** is caused to penetrate from the back side of the substrate **40** to be inserted into the reception portion **80** of the ferrite cover **60**, and thereby the ferrite cover **60** and the substrate **40** are fixed to each other.

Unlike the first through third embodiments, the current sensor **100c** of the fourth embodiment does not include the substrate cover **70**, and the ferrite cover **60** engages with the cutout portion **52** of the bus cover **50** alone. Therefore, as illustrated in FIG. **23B**, two sides surface of the ferrite cover **60** penetrated by the bus bar **10** engage with the cutout portion **52** of the bus cover **50**, and thereby the bus cover **50** and the ferrite cover **60** are positioned with respect to each other. The ferrite cover **60** is inserted from the upper direction of the ferrite **20**, and thus the ferrite cover **60** does not have a structure supporting the bus cover **50**, and the bus cover **50** is directly supported by the ferrite **20** as illustrated in FIG. **23C**.

As described above, even the current sensor **100c** of the fourth embodiment that does not use the substrate cover **70** can also engage the ferrite cover **60** with the bus cover **50** using the cutout portion **52** of the bus cover **50** as the first through third embodiments do.

FIGS. **24A** through **24C** are diagrams illustrating a structure of the current sensor **100c** in accordance with a variation of the fourth embodiment. FIG. **24A** is an external perspective view, FIG. **24B** is a cross-sectional view in which the current sensor **100c** is halved lengthwise, and FIG. **24C** is a plan view that views FIG. **24B** from the insertion direction of the bus bar **10**. Unlike FIGS. **23A** through **23C**, the recess portion **64** formed in the side surface of the ferrite cover **60** communicates with the opening portion **62** in the side surface of the ferrite cover **60**, and the ferrite cover **60** can be mounted on to the ferrite **20** from a horizontal direction. This configuration allows support the bus cover **50** by a support portion **82** of the ferrite cover **60** from a direction of gravity. The ferrite **20** breaks easily, but this configuration can prevent damage to the ferrite **20**.

The first through fourth embodiments configure a recess portion in the substrate cover **70** to have a step-like shape as illustrated in FIG. **12C**, but the configuration of the recess portion is not limited to the embodiments, and may be any that can engage with the cutout portion **52** of the bus cover **50**. For example, as illustrated in FIGS. **25A** through **25E**, a substrate cover of which the shape of the base of the recess portion is a simple rectangle may be used.

All examples and conditional language recited herein are intended for pedagogical purposes to aid the reader in understanding the invention and the concepts contributed by the inventor to furthering the art, and are to be construed as being without limitation to such specifically recited examples and conditions, nor does the organization of such examples in the specification relate to a showing of the superiority and infe-

riority of the invention. Although the embodiments of the present invention have been described in detail, it should be understood that the various change, substitutions, and alterations could be made hereto without departing from the spirit and scope of the invention.

What is claimed is:

1. A current sensor comprising:
 - a current bar through which a current flows;
 - a first cover that includes an opening into which the current bar is contactably inserted and includes a cutout portion formed in at least a part thereof;
 - a magnetic substance core that covers a part of the first cover into which the current bar is inserted and includes a gap;
 - a magnetic field measuring element located in the gap; and
 - a second cover that covers the magnetic substance core, and includes a side surface engaging with the cutout portion of the first cover.
2. The current sensor according to claim 1, further comprising:
 - a substrate to which the magnetic field measuring element is fixed, and in which a penetration hole that is penetrated by the current bar is formed; and
 - a third cover that covers the substrate and includes a side surface engaging with the cutout portion of the first cover.
3. The current sensor according to claim 2, wherein one side surface of the second cover and one side surface of the third cover contact with each other.
4. The current sensor according to claim 3, wherein
 - a raised portion is formed in at least one of the side surfaces of the second cover and the third cover contacting with each other, and
 - a recess portion is formed in at least the other of the side surfaces contacting with each other.
5. The current sensor according to claim 2, further comprising:
 - a fixing member that penetrates the substrate and the third cover.
6. The current sensor according to claim 1, wherein a cross section sectional shape of the opening in the first cover is stepped so as to accommodate current bars with different sizes.
7. The current sensor according to claim 1, wherein the current bar includes a recess portion formed in a position corresponding to the cutout portion of the first cover, and
 - a side surface of the second cover engages with the recess portion.
8. The current sensor according to claim 1, wherein the second cover includes a support portion that supports the first cover from a direction of gravity.
9. The current sensor according to claim 2, wherein a slit is formed in a side surface of the second cover, and the magnetic field measuring element is inserted into the gap of the magnetic substance core from the slit.
10. A current sensor comprising:
 - a current bar through which a current flows;
 - a first cover that covers the current bar and includes a cutout portion formed in at least a part thereof;
 - a magnetic substance core that covers at least parts of the current bar and the first cover and includes a gap;
 - a magnetic field measuring element located in the gap;
 - a second cover that covers the magnetic substance core and the magnetic field measuring element and at least parts of the current bar and the first cover, and is located so that

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a side surface of the second cover engages with the cutout portion of the first cover;
 a substrate to which the magnetic field measuring element is fixed, and in which a penetration hole that is penetrated by the current bar is formed; and
 a third cover that fixes the substrate to the first cover, wherein
 the magnetic field measuring element is inserted into the gap of the magnetic substance core from a slit formed in a side surface of the second cover, and
 the third cover covers the substrate and at least parts of the current bar and the first cover, and is located so that a side surface of the third cover engages with the cutout portion of the first cover.

11. The current sensor according to claim 10, wherein the second cover has a first side surface that is one of two side surfaces penetrated by the current bar and engages with the cutout portion of the first cover;

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the third cover has a first side surface that is one of two side surfaces penetrated by the current bar and engages with the cutout portion of the first cover, and
 second side surfaces, out of the two side surfaces of the second cover and the third cover, that fail to engage with the cutout portion, and that contact with each other.

12. The current sensor according to claim 11, wherein a raised portion is formed in at least one of the second side surfaces contacting with each other in the second cover and the third cover, and

a recess portion is formed in at least the other of the second surfaces.

13. The current sensor according to claim 10, further comprising:
 a fixing member that penetrates the substrate and the third cover.

* * * * *

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 9,250,273 B2
APPLICATION NO. : 13/933796
DATED : February 2, 2016
INVENTOR(S) : Naoyuki Nagao

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the claims

Column 10, Line 42, Claim 6

Delete "cross section sectional" and insert -- cross-sectional --, therefor.

Signed and Sealed this
Tenth Day of May, 2016

A handwritten signature in black ink, reading "Michelle K. Lee". The signature is fluid and cursive, with the first letters of each name being capitalized and prominent.

Michelle K. Lee
Director of the United States Patent and Trademark Office